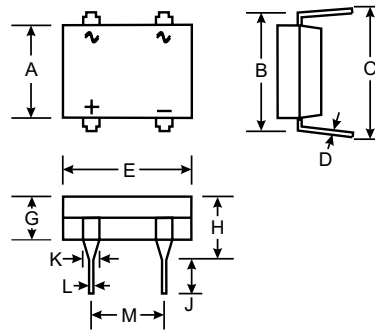


Features

- UL Recognized Component
- Ideal for Printed Circuit Board
- Glass Passivated Chip Junctions, Surge Overload Rating of 50A Peak
- Simple, Compact Structure for Trouble-free Performance
- Plastic Package - UL Flammability Classification 94V-0

Mechanical Data

- Terminals: Tin Plated Leads Solderable per MIL-STD-202, Method 208
- Case: Transfer Molded Epoxy
- Mounting Position: Any
- Polarity: Polarity Symbols Marked on Body
- Approx. Weight: 1.0 grams



DB-1		
Dim	Min	Max
A	6.10	6.60
B	7.11	8.13
C	8.13	9.40
D	0.20	0.38
E	-	9.40
G	-	3.30
H	-	5.51
J	2.80	3.68
K	1.02	1.40
L	0.51 Typical	
M	5.15 Typical	
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	DB 101	DB 102	DB 103	DB 104	DB 105	DB 106	DB 107	Unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Input Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Rectified Output Current @ $T_A = 40^\circ\text{C}$	$I_{(AV)}$	1.0							A
Peak Forward Surge Current Single Half Sine-wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	50							A
Maximum Instantaneous Forward Voltage drop per Element at $I_F = 1.0\text{A}$	V_F	1.1							V
Maximum Reverse DC Current at Rated DC Blocking Voltage per Element @ $T_A = 25^\circ\text{C}$ @ $T_A = 100^\circ\text{C}$	I_R	10 1.0							μA mA
Typical Thermal Resistance (Note 1)	$R_{\theta JA}$	40							K/W
Storage and Operating Temperature Range	T_J, T_{STG}	-55 to +150							$^\circ\text{C}$

- Notes:
1. Thermal resistance from junction to ambient mounted on PC board with 13mm x 13mm copper pads.
 2. 60 Hz resistive or inductive load.
 3. For capacitive load, derate current by 20%.

